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To the Honorable Commissioner of Patents

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JUL 25 1999 U.S. PTO  
09/244883

02/05/99

1. Name of conveying party(ies):

CHI-WEN LIU, CHIA-SHIUNG TSAI,  
JING-MENG LIU AND TSU SHIHWRD  
2-5-99

2. Name and address of receiving party(ies):

Name: Taiwan Semiconductor Manufacturing Company

Internal Address:

Street Address:

121 Park Ave. 3  
Science-Based Industrial Park  
City: Hsin-Chu Zip:  
Country: Taiwan, R.O.C.Additional name(s) or conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance

- ☒ Assignment ☐ Merger
- ☐ Security Agreement ☐ Change of Name
- ☐ other \_\_\_\_\_

Execution Date: 1/10/99Additional name(s) & address(es) attached? Yes ☐ No ☒4. Application number(s) or patent number(s): 09/244,883If this document is being filed together with a new application, the execution date of the application is: 1/10/99A. Patent Application No(s)B. Patent No(s)Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: GEORGE O. SAILE

Internal Address: \_\_\_\_\_

Street Address: 20 MCINTOSH DRIVECity: POUGHKEEPSIE State: NY ZIP: 126036. Total no. of applications and patents involved: 17. Total fee (37 CFR 3.41): \$ 40.00

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Signature

February 30 1999

Date

Total number of pages comprising copy sheet: 3

PATENT

REEL: 9753 FRAME: 0155

For ☒ U.S. and/or ☒ Foreign Rights

For ☒ Application or ☐ U.S. Patent

By ☒ Inventor(s) or ☐ Present Owner

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

#### ASSIGNOR:

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#### ASSIGNEE:

**Taiwan Semiconductor Manufacturing Co. Ltd.**  
**121 Park Ave. 3**  
**Science-Based Industrial Park**  
**Hsin-Chu, Taiwan, R.O.C.**  
**Taiwan, R.O.C.**  
Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

- ☒ the entire right, title and interest
- ☐ an undivided \_\_\_\_\_ percent (\_\_\_%) interest for the United States and its territorial possessions  
(check the following box/f foreign rights are also to be assigned)
- ☒ and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

New Bulk metal structure For Bonding Pad In Periphery  
And Bulk Metal In Cell For Damascene Application

and which is found in

- (a) ☒ U.S. patent application executed on even date herewith  
(b) ☐ U.S. patent application executed on \_\_\_\_\_  
(c) ☐ U.S. application serial no. \_\_\_\_\_ filed on \_\_\_\_\_  
(d) ☐ U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_  
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(e) ☐ and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

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IN WITNESS WHEREOF, I / We have signed this

1/10/99 (Date of signing)

**WARNING** Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Chi-Wen Liu  
Signature of ASSIGNOR(S)  
Chia Shung Tsai  
Tsu Shih  
Tung Heng Liu

If ASSIGNOR is a legal entity complete the following information

\_\_\_\_\_  
Type or print the name of the above person authorized to sign on  
behalf of ASSIGNOR

\_\_\_\_\_  
Title

Note: No witnessing, notarization or legalization is necessary. If the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

\_\_\_ Notarization of Legalization Page Added.